

# 1N4245 - 1N4249

## GLASS PASSIVATED JUNCTION SILICON RECTIFIERS

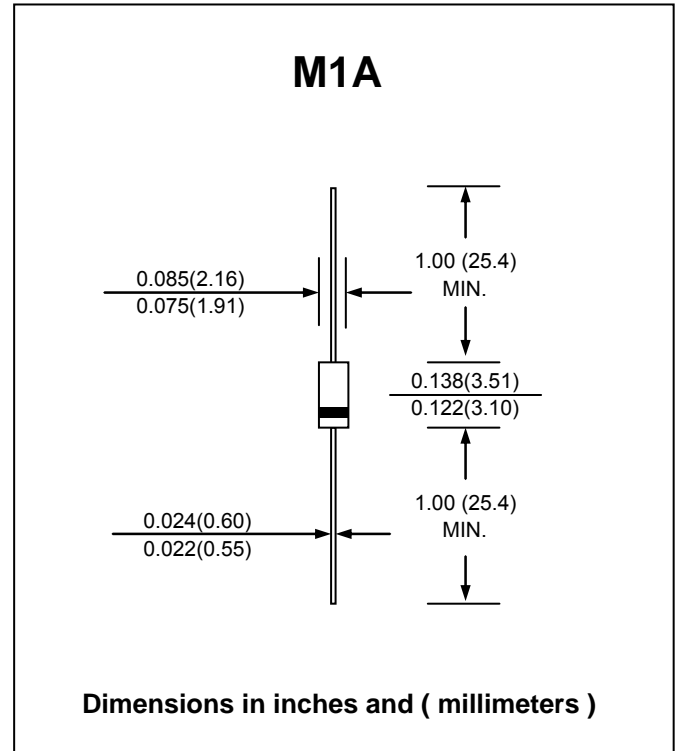
**PRV : 200 - 1000 Volts**  
**I<sub>o</sub> : 1.0 Ampere**

### FEATURES :

- \* Glass passivated chip
- \* High forward surge current capability
- \* High reliability
- \* Low reverse current
- \* Low forward voltage drop
- \* Pb / RoHS Free

### MECHANICAL DATA :

- \* Case : M1A Molded plastic
- \* Epoxy : UL94V-O rate flame retardant
- \* Lead : Axial lead solderable per MIL-STD-202, Method 208 guaranteed
- \* Polarity : Color band denotes cathode end
- \* Mounting position : Any
- \* Weight : 0.20 gram (approximately)



### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load.  
 For capacitive load, derate current by 20%.

RATING	SYMBOL	1N4245	1N4246	1N4247	1N4248	1N4249	UNIT
Maximum Working Peak Reverse Voltage	V <sub>RWM</sub>	200	400	600	800	1000	V
Minimum Breakdown Voltage @ 100 μA	V <sub>BR(MIN)</sub>	240	480	720	960	1150	V
Maximum Average Forward Current at Ta = 55 °C	I <sub>F(AV)</sub>	1.0					A
Peak Forward Surge Current 8.3 ms Single half sine wave Superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	25					A
Maximum Forward Voltage at I <sub>F</sub> = 3.0 A	V <sub>F</sub>	1.3					V
Maximum Reverse Current at V <sub>RWM</sub> , Ta = 25 °C at V <sub>RWM</sub> , Ta = 150 °C	I <sub>R</sub>	1.0					μA
	I <sub>R(H)</sub>	150					
Maximum Reverse Recovery Time ( Note 1 )	T <sub>rr</sub>	5.0					μs
Thermal Resistance , Junction to Lead (Note 2)	R <sub>θJL</sub>	42					°C/W
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +175					°C

#### Notes :

- (1) Reverse Recovery Test Conditions : I<sub>F</sub> = 0.5 A, I<sub>RM</sub> = 1.0 A, I<sub>R(REC)</sub> = 0.25 A.
- (2) At 3/8"(10 mm) lead length form body.